

# 阿尔法免洗无松香助焊剂NR205

产品名称	阿尔法免洗无松香助焊剂NR205
公司名称	深圳市中图时予科技有限公司
价格	面议
规格参数	
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## 产品详情

ALPHA NR205免洗无松香助焊剂  
SM 1008-2

NO-CLEAN, LOW RESIDUE FLUX

### DESCRIPTION

Alpha NR205 is a halide-free, rosin/resin free, low solids, no-clean flux. It is formulated for wave soldering of through-hole, mixed technology and surface mount assemblies. The flux is particularly effective when soldering in an inert atmosphere. The flux produces a tack-free surface with high surface insulation resistance and very little residue to interfere with electrical testing. Alpha NR205 fully conforms to the requirements of Bellcore TR-NWT-000078. The flux has been specifically formulated to resist degradation in surface insulation resistance and electromigration, even in situations where the flux does not experience soldering

temperatures and when heavy levels of flux have been applied. The residues are non-corrosive and do not cause "greening" when in contact with copper or copper-bearing alloys.

Alpha NR205 is particularly well-suited for touch-up/rework when supplied in a flux pen. Alpha " WriteFlux " pens make local flux application an easily controlled process.

## FEATURES & BENEFITS

- High activity
- Meets bellcore requirements & other critical sir tests
- Very safe residues
- Non-corrosive residues
- Good soldering in air; excellent soldering in nitrogen for low defects
- High reliability assemblies, even when the flux does not experience soldering temperatures
- Excellent for touch-up/rework applications
- Will not cause "greening" on exposed copper/copper alloys

## APPLICATION

Alpha NR205 flux is designed for foam, spray, and wave applications. Topside preheat temperatures of 80-105 ° C (180-220 ° F) are recommended. Flux solids can be monitored using Alpha's Flux Solids Control Kit #3. If thinning is required, the use of Alpha 493 thinner is recommended. For applications which specify cleaning, a water cleaning step with Alpha 2110 saponifier or Alpha Autoclean 40, after soldering, will remove any slight traces of flux residues.

For application via the flux pen, the nib should be lightly wiped on and around the solder joint to be reworked. Once a suitable amount of flux has been applied the manual soldering operation can be performed.

## Technical Specifications

Appearance: Clear, colorless liquid

Solids Content, wt/wt: 2.15

Specific Gravity @ 25 ° C (77 ° F): 0.797 ± 0.002

Acid Number (mg KOH/g): 16.5 ± 1.0

Halides: NONE

Flash Point (T.C.C.): 13 ° C (56 ° F)

Recommended Thinner: 493

IPC J-STD-004 Designation ORL0